EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("6548121").PN.	USPAT; USOCR	OR	OFF	2009/02/19 16:58
S2	1180	"ciba specialty chemicals corporation".as.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:03
S3	5	"ciba specialty chemicals corporation".as. and strongly adherent coatings	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S4	5	"ciba specialty chemicals corporation".as. and strongly adherent coating	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S5	1	10/566743.app.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
S6	1	("7455891").PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:00
S7	8	(("7455891") or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362")).PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:09
S8	9	(("7455891") or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362") or ("6399805")).PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:14
S9	108	("3669951" | "3936305" | "4082679" | "4199421" | "4226763" | "4246315" | "4275004" | "4278589" | "4292152" | "4298738" | "4315848" | "4324744" | "4347180" | "4385109" | "4466993" | "4533652" | "4567106" | "4681905" | "4684679" | "4684680" | "4710523" | "4737593" | "4792632" | "4861916" | "4868246" | "4965294" | "4990364" | "5053246" | "5080994" | "5106891" | "5108835" | "5116534" | "5153284" | "5166355" | "5168087" | "5196142" | "5218009" | "5250698" | "5252403" | "5278314" | "5280124" | "5292890" | "5330539" | "5360850" | "5399770" | "5436349" | "5456728" | "5472992" | "5504236" | "5516914" | "5549847" | "5554760" | "5563242" | "5574166" | "5607987" | "5646088" | "5935900" | "5942290" | "5955514" | "5990189" | "6099122" | "6190423" | "6329445" | "6344505" | "6361925" | "6376065" | "6399805" | "6407254" | "6548121" | "6733847").PN. OR ("6251963" | "6368362" | "6399805" | "6486228" | "6515051" | "6548121" | "6733847" | "6803392" | "7455891").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:21
S10	15	("4199421" | "4246315" | "4466993" | "4567106" | "4990364" | "5053246" | "5252403" | "6099122" | "6548121" | "6733847").PN. OR ("6548121" | "6733847" | "7455891").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:22
S11	21169	427/533,535,536,517,407.1-412.5,532-559,517,509,512,513,517,518,519,520,535,536,538,551,553,554,556,407.2,409,412,412.1,419.2.ccls. or 430/311.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27

S12	5299	427/533,509.ccls. or 430/311.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S13	211	(adhere$4 or adhesion or glu$3 or bond$3) with metallized with (organic or polymer) with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S14	139	(adhere$4 or adhesion or glu$3 or bond$3) with metallized with (organic or polymer) with substrate and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S15	13	(adhere$4 or adhesion or glu$3 or bond$3) with metallized with (organic or polymer) with substrate and @PY<"2004" and S11	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S16	7	circuit and photoinitiator with adhesion with metal	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
S17	183	circuit and photoinitiator with adhesion and (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S18	13	circuit and photoinitiator with adhesion with (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S19	613	circuit and photoresist with adhesion with (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S20	283	circuit and photoresist with adhesion with (metal or copper) and plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S21	47	circuit and photoresist with adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19
S22	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV) with adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34

S23	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV) and adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S25	46	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV) with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
S27	2	"20030129322".did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
S28	13	solder mask with (cvd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
S29	692	solder with (cvd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
S30	5	solder with (cvd or evaporate or pvd) with (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
S31	149	solder with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S32	12645	metal with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S33	45	solder with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44

S34	580	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S35	25	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S36	3	wiring board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
S37	121	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004" and cmp	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
S38	1	("6524950").PN.	USPAT; USOCR	OR	OFF	2009/02/20 19:21
S39	600	photoresist with (lift off or liftoff) and polymer$2 with substrate and metal	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S40	189	photoresist with (lift off or liftoff) and polymer$2 with substrate and metal and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S41	12	photoresist with (lift off or liftoff) and polymer$2 with substrate and metal and develop$3 with (solvent or mechanical$3) and dry with (oven or IR or hot gas$2 or microwave or roller) and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
S42	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop$3 with (solvent or mechanical$3) and dry with (oven or IR or hot gas$2 or microwave or roller) and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S43	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop$3 with (solvent or mechanical$3) and dry with (oven or IR or hot gas$2 or microwave or roller) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S44	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop$3 and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34

S45	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer$2 or metal$3 or glass or metal oxide) with substrate and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42
S46	132	(lithography or photoresist) with (lift off or liftoff) and (polymer$2 or metal$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:43
S47	265	427/98.5.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:01
S48	95	427/98.5.ccls. and (resist or photoinitiator)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:02
S49	26	427/98.5.ccls. and (resist or photoinitiator) and plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:03
S50	2	10/502208.app.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 15:36
S51	1	trimethylbenzoyl allyl phenyl phosphine oxide	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/24 13:17
S52	12	("20020026049" | "20050147919" | "6399805" | "6548121" | "6589550" | "6733847").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/25 12:09
S53	2	(09/871373 | 10/502208).APP.	USPAT; USOCR	ADJ	ON	2009/02/25 12:10
S54	1	wo-0024527-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/25 14:05
S55	0	EP-0475592-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27

S56	0	EP-0475592.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27
S57	0	EP0475592.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27
S58	2	"US 20060257681"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2010/03/24 14:32
S59	22	radiation with curing with dosage with crosslinking	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 15:58
S60	98	primer with photoinitiator with (irradiat$3 or cur$3 or crosslink$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 11:44
S61	2	jp-2001083301-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 12:23
S62	1	2001-338377.NRAN.	DERWENT	ADJ	ON	2010/04/01 12:24
S63	1	2001-338377.NRAN.	DERWENT	ADJ	ON	2010/04/01 12:24
S64	150	427/492.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:08
S65	655	427/487.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:24
S66	1148	427/508.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
S67	775	427/510.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27

S68	748	427/517-519.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
S69	115	427/517-519.ccls. and primer	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
S70	1	("4,634,602").PN.	USPAT; USOCR	OR	OFF	2010/04/02 08:51
S71	31	("3876432" | "3899611" | "4025407" | "4128600" | "4169732" | "4205018" | "4295947" | "4342793" | "4374963" | "4391855" | "4425207").PN. OR ("4634602").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 09:01
S77	15	("2873241" | "3036930" | "3892575" | "4303697").PN. OR ("4778724").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 10:34
S78	15	("2873241" | "3088791" | "3131138" | "3453195").PN. OR ("3892885").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 11:25
S79	23	("3661614" | "4188451" | "4190681" | "4197335" | "4198465" | "4218294" | "4222835" | "4264658" | "4384026" | "4396678").PN. OR ("4902578").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 15:51
S81	0	DE-19953433-$.did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:55
S82	0	DE-1995003433-$.did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:56
S83	0	DE-95003433-$.did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:56
S84	0	DE-953433-$.did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:56
S85	1611	427/508-510.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 17:00
S86	204	427/508-510.ccls. and metal$4 and primer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 17:01
S87	148	427/508-510.ccls. and metal$4 with (coating or layer or film) and primer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 17:01
S88	7	427/508-510.ccls. and metal$4 with (coating or layer or film) and primer with ($5initiator) with (cur$3 or crosslink$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 15:48
S89	8	427/508-510.ccls. and metal$4 and primer with ($5initiator) with (cur$3 or crosslink$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 15:51
S90	185	427/508-510.ccls. and metal$4 with substrate and ($5initiator) with (cur$3 or crosslink$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 15:51
S91	0	427/508-510.ccls. and metal$4 with substrate and (multicoat$3 or multilayer) and ($5initiator) with cur$3 with uncur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:41
S92	2	427/508-510.ccls. and (multicoat$3 or multilayer) and ($5initiator) with cur$3 with uncur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:41
S93	2	427/508-510.ccls. and (multicoat$3 or multilayer) and ($5initiator) with cur$3 with (stable)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:42
S94	57	427/508-510.ccls. and (multicoat$3 or multilayer) and photoinitiator with cur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:42
S95	49	427/508-510.ccls. and (multicoat$3 or multilayer) and photoinitiator with cur$3 and metal$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:43

S96	0	427/508-510.ccls. and (multicoat$3 or multilayer) and photoinitiator with partial$2 cur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S97	2	427/508-510.ccls. and photoinitiator with partial$2 cur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S98	4	427/508-510.ccls. and photoinitiator with partial$2 near5 cur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S99	5	427/508-510.ccls. and partial$2 near5 cur$3 with unsaturated	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S100	195	427/508-510.ccls. and partial$2 near5 cur$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
S101	109	427/508-510.ccls. and partial$2 near5 cur$3 and photoinitiator	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
S102	151	427/508-510.ccls. and partial$2 near5 cur$3 and metal$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
S103	148	427/508-510.ccls. and metal$4 with (coating or layer or film) and primer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S104	126	427/508-510.ccls. and partial$2 near5 cur$3 and metal$3 not S103	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S105	22	427/508-510.ccls. and partial$2 near5 cur$3 and metal$3 not S103 and multilayer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S106	23	427/508-510.ccls. and partial$2 near5 cur$3 and metal$3 not S103 and multilayer$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S107	1	wo-0232201-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:32
S108	2	jp-2001217529-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:42
S109	2	jp-2001046940-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:46
S110	1	2001-567393.NRAN.	DERWENT	ADJ	ON	2010/04/07 09:48
S111	5	427/508-510.ccls. and metal$3 with (evaporat$3 or sputter$3) and multilayer$3 and ("UV/VIS" or UV or ultraviolet) with cur$4 and photoinitiator and acrylate	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/07 13:57
S112	1	"20040011288".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/07 17:13

EAST Search History (Interference)

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4/8/2010 1:53:00 PM
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